

NOTES

UNLESS OTHERWISE SPECIFIED:

1. RESISTANCE VALUES IN OHMS.
2. REFERENCE DESIGNATORS USED:

A. INTEGRATED CIRCUITS: U1-U13

B. CERAMIC CAPS: C1 - C63, C65 - C110

C. LOW ESL TANTALUM CAPS: CT1-CT15

D. RESISTORS: R1-R81

E. RESISTOR PACKS: RP1-R21

F. CONNECTORS/HEADERS: JP1 - JP2, JH1, J1, P1 - P3

G. CRYSTALS: Y1-Y3

H. EMI FILTERS: E1 - E3

I. FERRITE BEADS: L1-L3

J. FUSES: F1-F2

K. TEST POINTS: TP1-TP2
3. OBSERVE THE FOLLOWING LAYOUT NOTES:

FORMAT: PAGENUMBER.NOTENUMBER

2.1, 2.2, 2.3, 3.1, 3.2, 3.3, 3.4, 4.1, 4.2, 4.3, 5.1, 5.2,

5.3, 6.1, 6.2, 6.3, 6.4, 6.5, 6.6, 7.1, 7.2, 7.3, 7.4, 7.5, 8.1,

8.2, 9.1, 9.2, 9.3, 10.1, 10.2, 10.3 11.1, 11.2, 12.1,

12.2, 12.3, 12.4, 12.5, 12.6, 12.7
4. ALL 0100nf AND 220nf CAPACITORS ARE DECOUPLING CAPS UNLESS OTHERWISE NOTED. THE ARE SHOWN ON THE PAGE WITH THE INTEGRATED CIRCUITS THEY SHOULD BE PLACED NEAR.
5. BOARD PROPERTIES

A. ROUTE TO WITHIN 10% OF MANHATTAN DISTANCE - DEVIATIONS PERMITTED TO MEET AC TIMINGS GOALS

B. 50 OHM MATCHED IMPEDANCE

C. OUTER LAYERS 0.5 OZ CU /W 0.5 OZ AU PLATING

D. INNER LAYERS 1.0 OZ CU

E. FR4 BOARD MATERIAL

F. MINIMUM TRACE WIDTH/SPACING 4 MILS

G. MINIMUM VIA SIZE 10/19 MIL

H. BOARD SHALL MEET PCI 3.3V 32BIT SHORT-FORM EXPANSION CARD SPECIFICATION

J. THERMAL RELIEFS SHALL NOT BE USED EXCEPT ON THROUGH-HOLE PARTS

K. STACKUP: (4 LAYER)

1. TOP - SIGNAL ROUTING

2. GROUND PLANE

3. SPLIT POWER (3V3 & CVDD)

4. BOTTOM - SIGNAL ROUTING

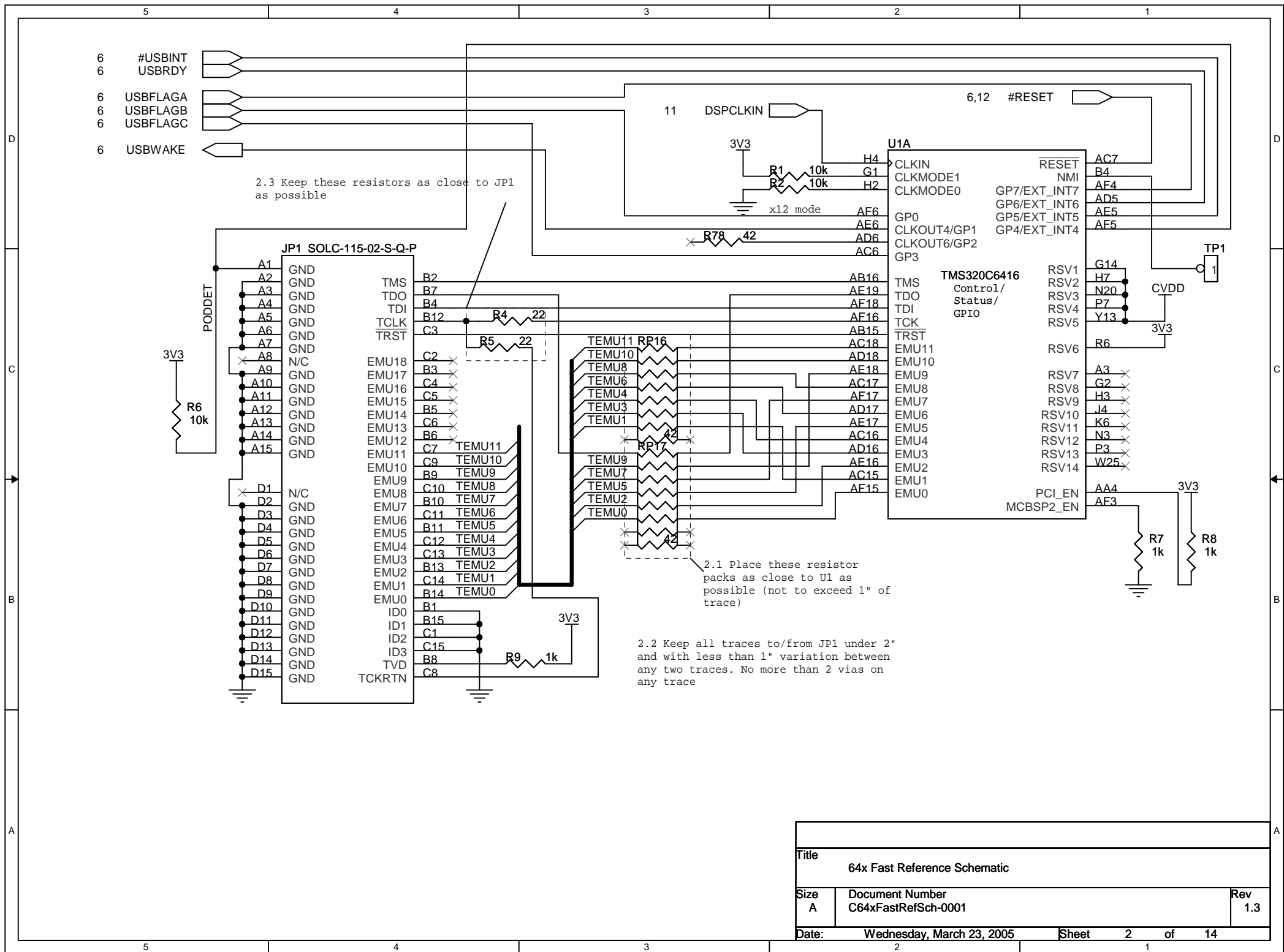
L. ALL PARTS AND IC PIN 1 DESIGNATORS SHALL BE MARKED ON THE SILK SCREEN

Rev	Description	Owner
1.0	Preliminary Design	TCH
1.1	Fixed CVDD feedback open Added notes for power supply design improvements Altered default Rs for CLK freq select	TCH
1.2	Fixed USB OE Problem	TCH
1.3	Changes for EMI	TCH
1.4	Added R80 & R81 Pullups on USB bridge	TCH

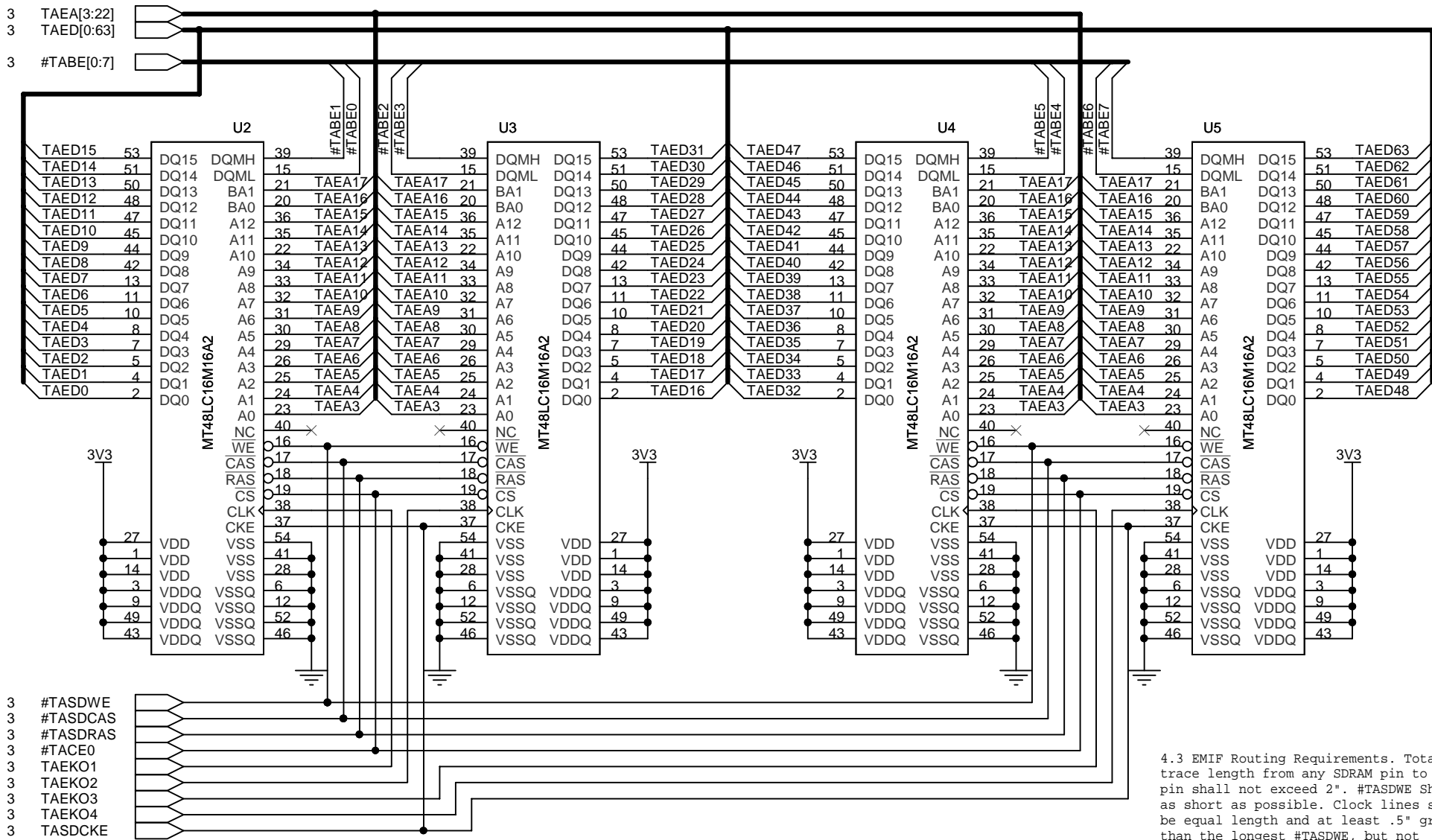
SCHEMATIC CONTENTS

1. Notes and Contents
2. 64x Control / Status / GPIO / EMU
3. 64x EMIFA & Terminations
4. EMIFA SDRAM
5. 64x EMIFB & Terminations
6. USB Bridge
7. 64x PCI
8. 64x UTOPIA / McBSP1
9. 64x McBSP0 / Timers
10. 64x Power
11. Clocks
12. Power Converters

Title		
64x Fast Reference Schematic		
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A	C64xFastRefSch-0001	1.3
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4.3 EMIF Routing Requirements. Total trace length from any SDRAM pin to DSP pin shall not exceed 2". #TASDWE shall be as short as possible. Clock lines shall be equal length and at least .5" greater than the longest #TASDWE, but not exceeding 2.75". EMIF A traces must pass IBIS timing check

4.1 Bypass Caps. Place 4 near each SDRAM

4.2 Bypass Caps. Place 1 between each SDRAM

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Boot Configuration

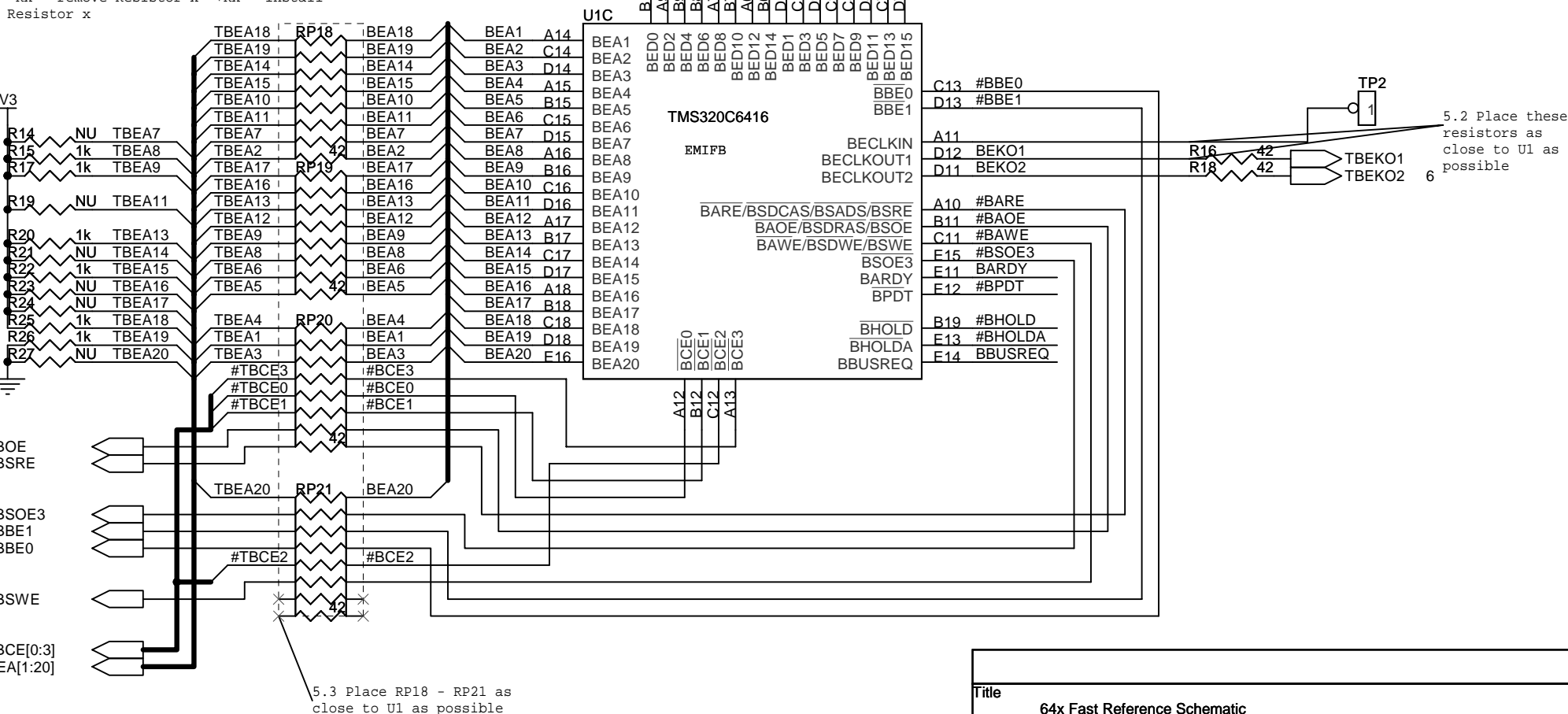
Endianness	Big Little*	+R27 -R27
Bootmode	None PCI* ROM	+R26 -R25 +R26 +R25 -R26 -R25
AECLKIN Select	AECLKIN* CPU/4 CPU/6	-R24 -R23 -R24 +R23 +R24 -R23
BECLKIN Select	BECLKIN CPU/4 CPU/6*	-R22 -R21 -R22 +R21 +R22 -R21
PCI Autoinit	Disable Enable*	-R20 +R20
UTOPIA Enable	Disable* Enable	-R19 +R19
Reserved	C6414 C6415 C6416*	-R17 -R15 -R14 +R17 -R15 -R14 -R17 +R15 +R14

* indicates configuration on schematic

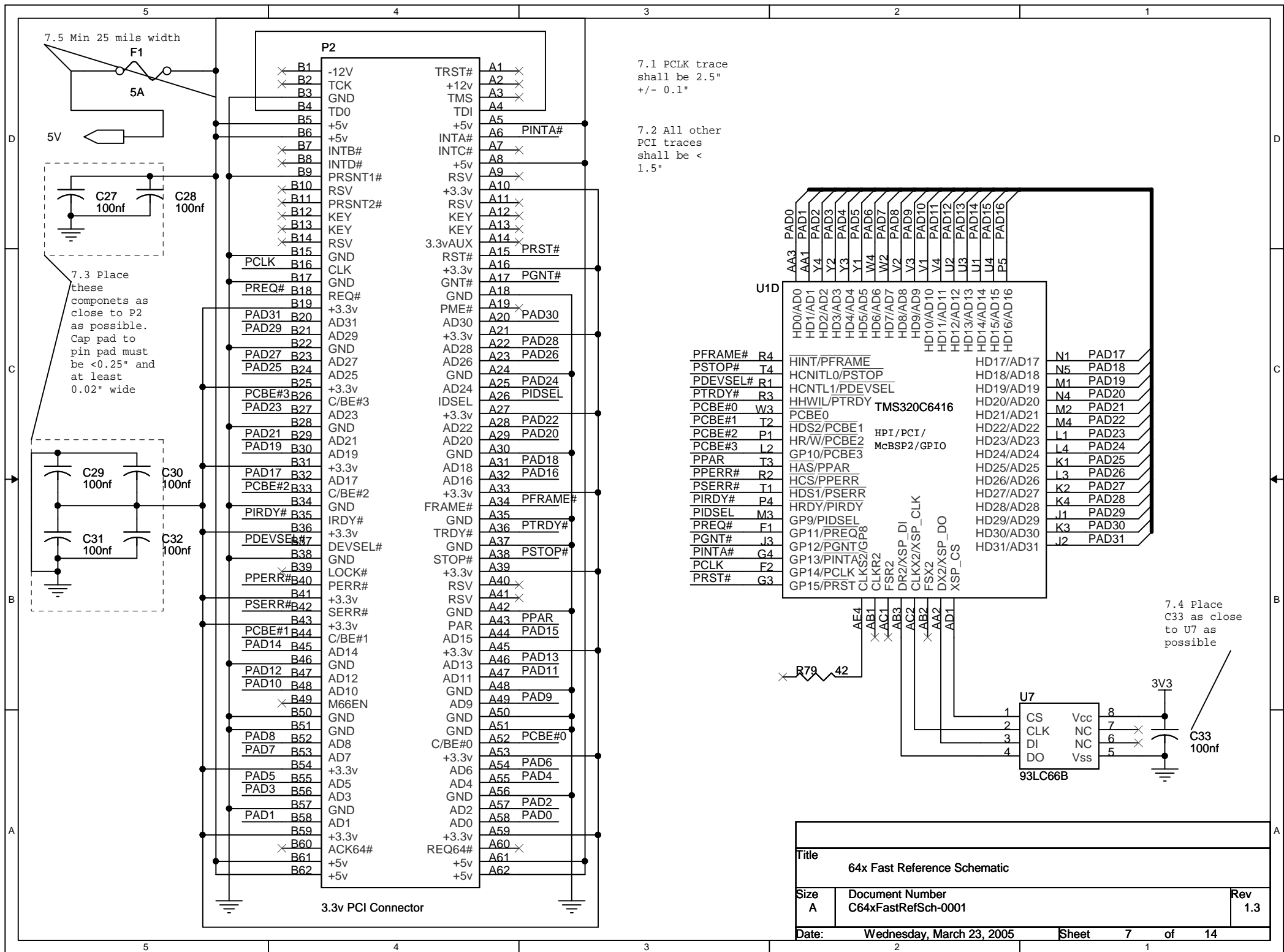
-Rx = remove Resistor x +Rx = install

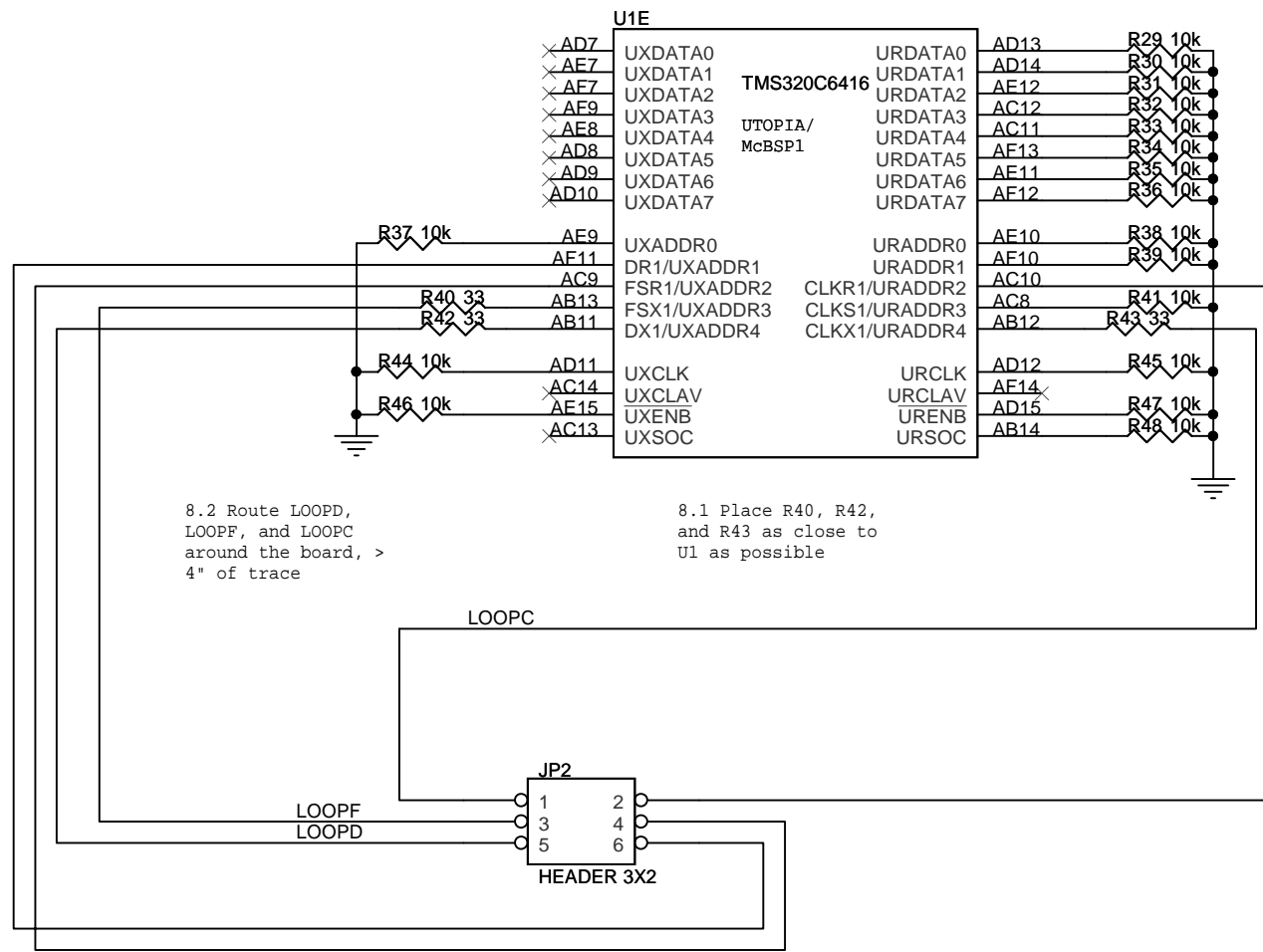
Resistor x

5.1 These Resistor packs should be placed approximately halfway between the DSP and U6

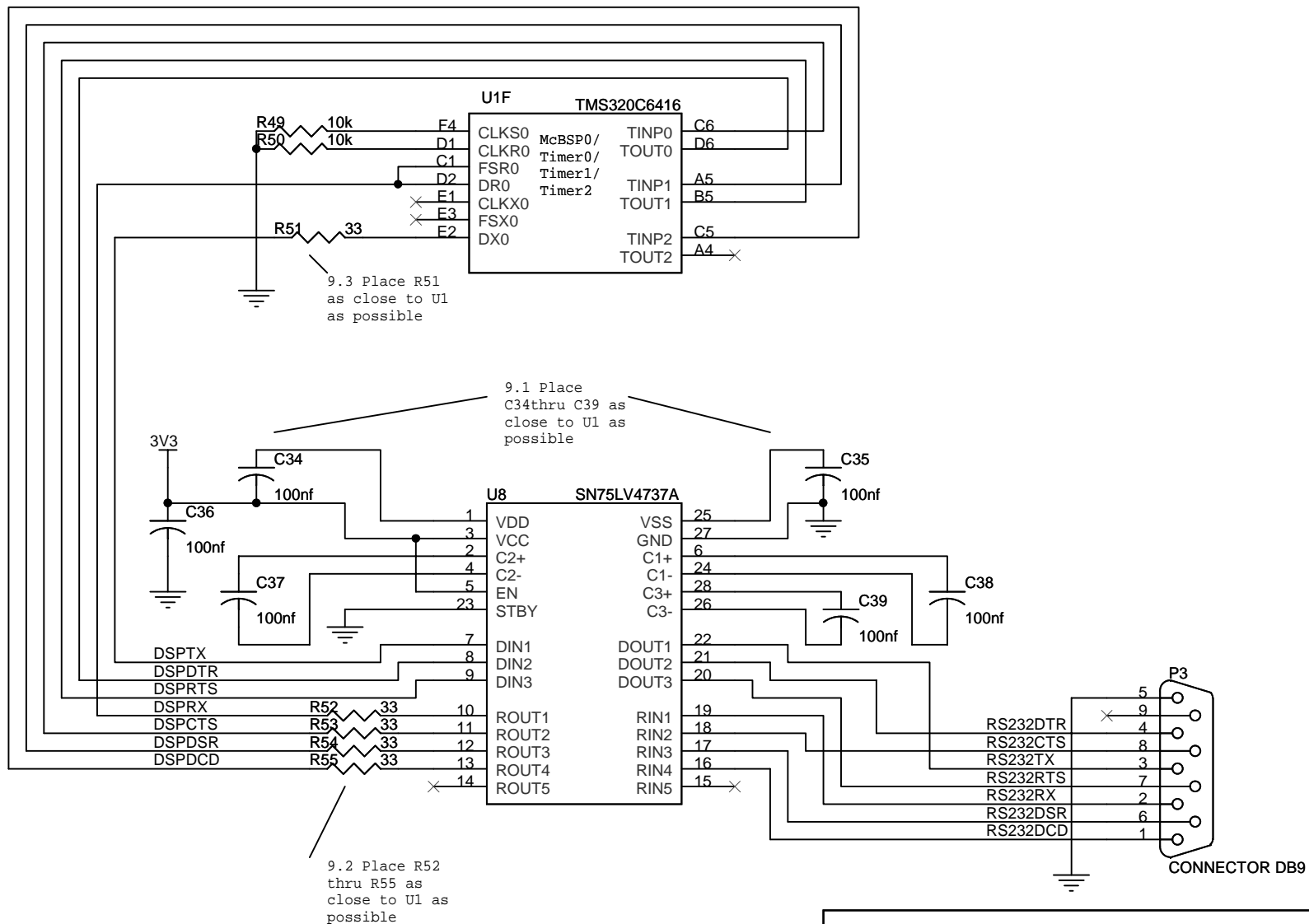


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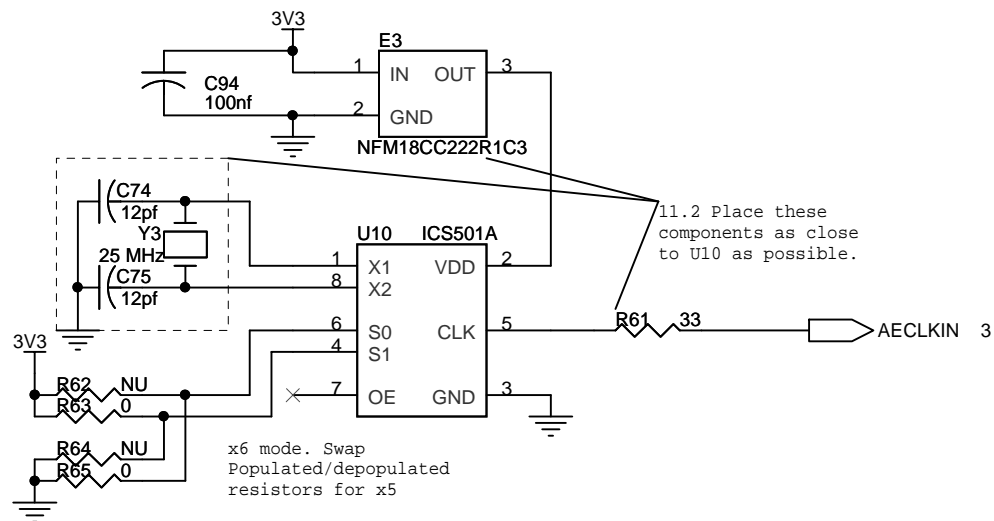
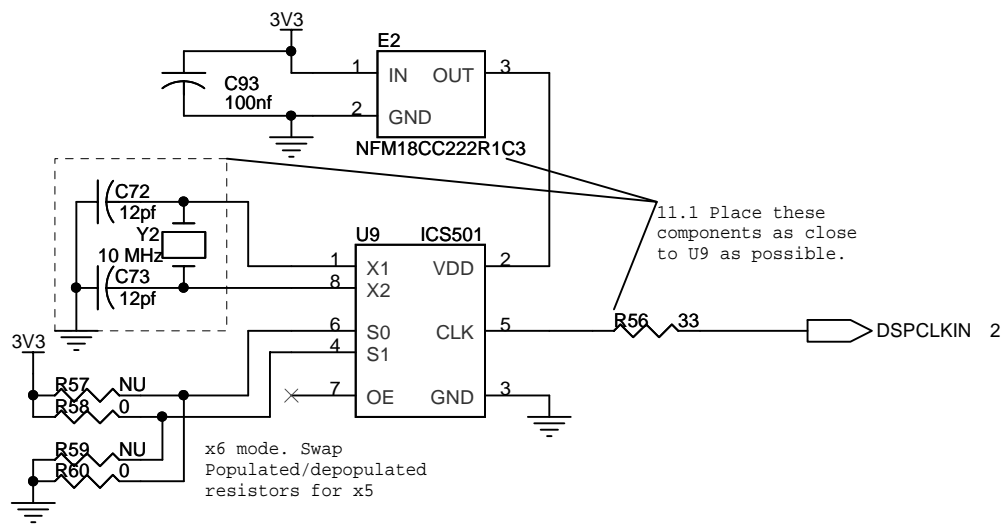




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